

# INTERNATIONAL STANDARD

## NORME INTERNATIONALE



**Field device integration (FDI) –  
Part 103-1: Profiles – PROFIBUS**

**Intégration des appareils de terrain (FDI) –  
Partie 103-1: Profils – PROFIBUS**



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## FIELD DEVICE INTEGRATION (FDI) –

## Part 103-1: Profiles – PROFIBUS

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The text of this standard is based on the following documents:

CDV	Report on voting
65E/354/CDV	65E/417/RVC

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62769 series, published under the general title *Field Device Integration (FDI)*, can be found on the IEC website.

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- c) methods and apparatus to reduce memory requirements for process control system software applications, see Patent Family US2013232186;
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## FIELD DEVICE INTEGRATION (FDI) –

### Part 103-1: Profiles – PROFIBUS

#### 1 Scope

This part of IEC 62769 specifies an FDI profile of IEC 62769 for IEC 61784-1\_CP 3/1 (PROFIBUS DP)<sup>1</sup> and IEC 61784-1\_CP3/2 (PROFIBUS PA).

#### 2 Normative references

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61784-1, *Industrial communication networks – Profiles – Part 1: Fieldbus profiles*

IEC 61804 (all parts), *Function blocks (FB) for process control and Electronic Device Description Language (EDDL)*

IEC 62541-100:2015, *OPC unified architecture – Part 100: Device Interface*

IEC 62769-2, *Field Device Integration (FDI) – Part 2: FDI Client*

NOTE 1 IEC 62769-2 is technical identical to FDI-202.

IEC 62769-4, *Field Device Integration (FDI) – Part 4: FDI Packages*

NOTE 2 IEC 62769-4 is technically identical to FDI-2024.

IEC 62769-5, *Field Device Integration (FDI) – Part 5: FDI Information Model*

NOTE 3 IEC 62769-5 is technically identical to FDI-2025.

IEC 62769-7, *Field Device Integration (FDI) – Part 7: FDI Communication Devices*

NOTE 4 IEC 62769-7 is technically identical to FDI-2027.

PI Order No. 2.122:2008, *Specification for PROFIBUS – Device Description and Device Integration – volume 1: GSD, V5.1, July 2008: GSD*; available at <[www.PROFIBUS.com](http://www.PROFIBUS.com)>

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